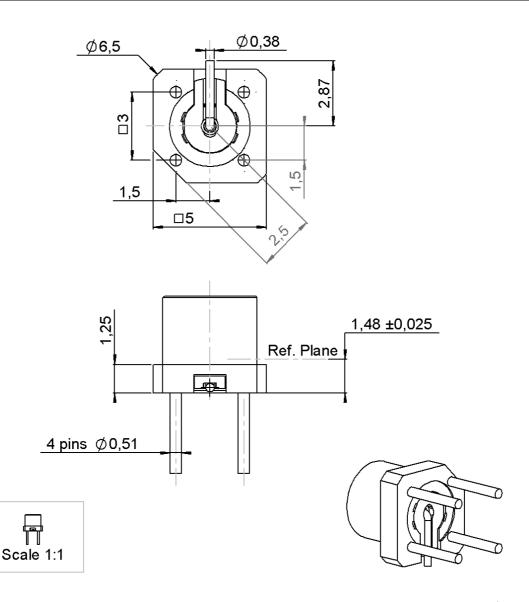
R222.940.100

FULL DETENT-TAPE AND REEL BY 500

Series: **SMP-COM**



All dimensions are in mm.

			7
_	COMPONENTS	MATERIALS	PLATING (μm)
	BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BRASS - PEEK	NPGR NPGR - - -

Issue: 1120 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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PACKAGING

Standard Unit Other 500 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-12.4*} \;\; \text{GHz} \end{array}$

VSWR 1.1** + 0,0000 x F(GHz) Maxi

Insertion loss $0.12 \sqrt{F(GHz)} dB Maxi$ RF leakage -(NA - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 500 M Ω mini

ENVIRONMENTAL

Operating temperature -55/+125 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

*ROS 1.35 at 6GHz **ROS at 6GHz

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3650** g

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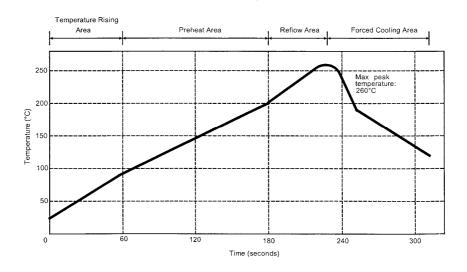
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SOLDER PROCEDURE

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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necessary.

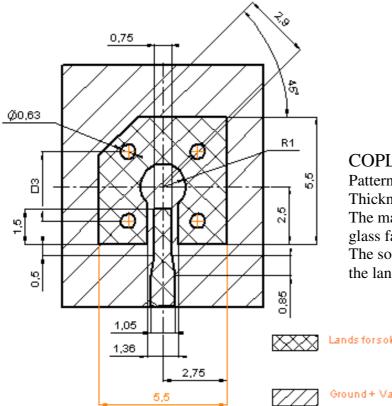


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STANDARD PAD(For ROGERS 4350)



COPLANAR LINE

Pattern and signal are on the same side.

Thickness of PCB: 1.6mm

The material of PCB is the epoxy resin of

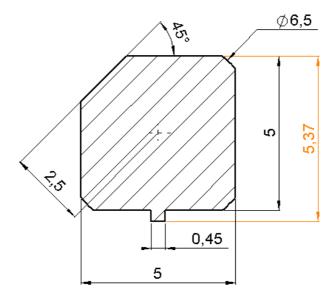
glass fabrics bacs (ER:4.8).

The solder resist should be printed exept for the land pattern on the PCB.

Lands for solder paste

Ground + Varnish

SHADOW OF RECEPTACLE FOR VIDEO CAMERA



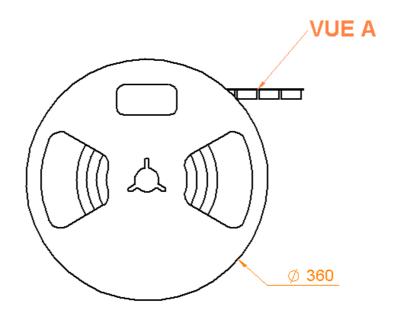
Issue: 1120 C In the effort to improve our products, we reserve the right to make changes judged to be



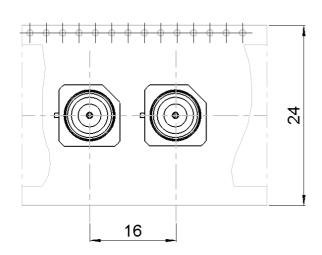
FULL DETENT-TAPE AND REEL BY 500

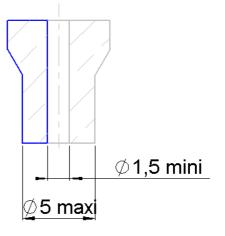
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AIR SUNCTION





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